

HSD276A

Silicon Schottky Barrier Diode for Detector

REJ03G0604-0100
(Previous: ADE-208-1385)
Rev.1.00
Apr 15, 2005

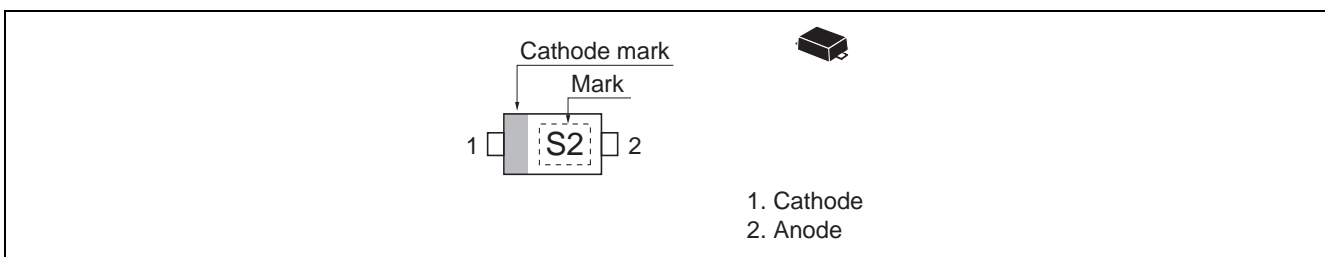
Features

- High forward current, Low capacitance.
- Super small Flat Lead Package (SFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
HSD276A	S2	SFP	PUSF0002ZB-A (SFP)

Pin Arrangement



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Repetitive peak reverse voltage	V _{RRM}	5	V
Reverse voltage	V _R	3	V
Average rectified current	I _O	30	mA
Junction temperature	T _j	125	°C
Storage temperature	T _{stg}	-55 to +125	°C

Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse voltage	V _R	3.0	—	—	V	I _R = 1 mA
Reverse current	I _R	—	—	50	μA	V _R = 0.5 V
Forward current	I _F	35	—	—	mA	V _F = 0.5 V
Capacitance	C	—	—	0.85	pF	V _R = 0.5 V, f = 1 MHz
ESD-Capability *1	—	30	—	—	V	C = 200 pF, R = 0 Ω, Both forward and reverse direction 1 pulse.

Notes: 1. Failure criterion ; I_R > 100 μA at V_R = 0.5 V

2. Please do not use the soldering iron due to avoid high stress to the SFP package.

Main Characteristic

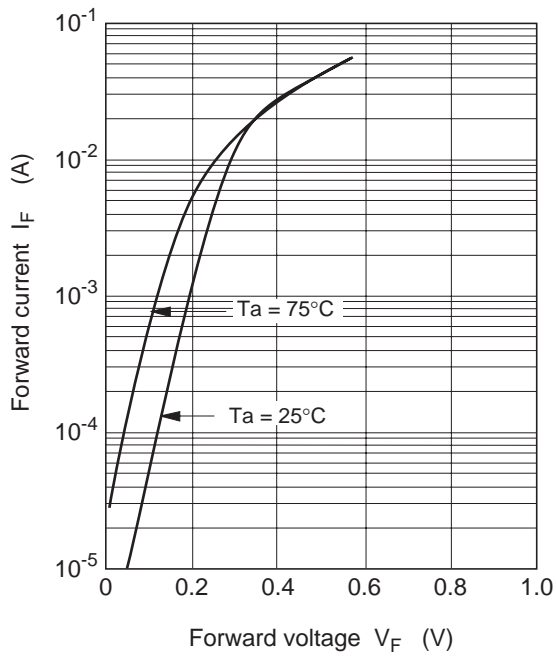


Fig.1 Forward current vs. Forward voltage

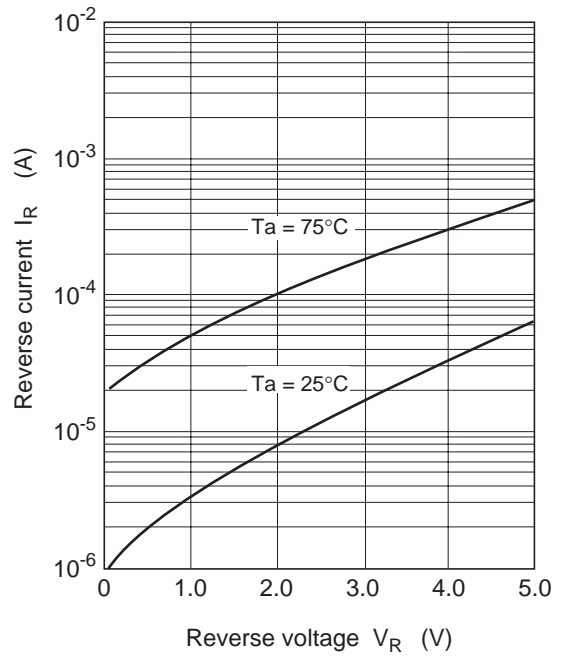


Fig.2 Reverse current vs. Reverse voltage

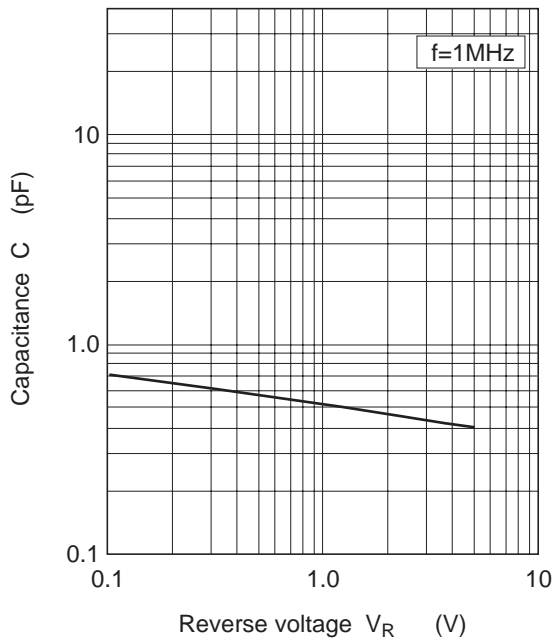
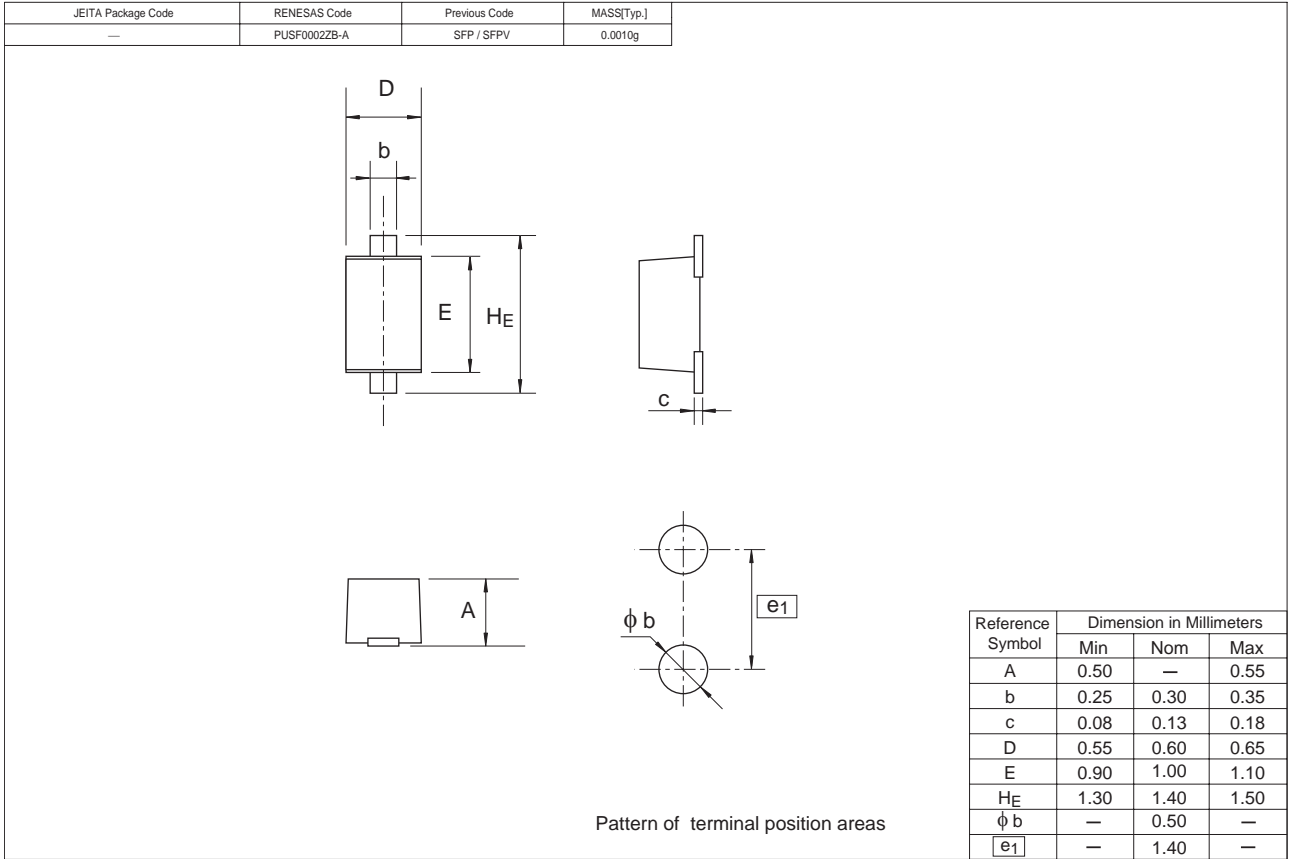


Fig.3 Capacitance vs. Reverse voltage

Package Dimensions



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